



Materials Declaration Form

IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D

* : Required Field

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	27/6/2016
Contact Name *	Refer to Supplier comment section	Contact Title	Refer to Supplier comment section
Authorized Representative *	Patrick PERILLAT	Representative Title	MDG - CPD Material Declaration Champion
Representative Phone *	Refer to Supplier Comment section	Representative Email *	Refer to Supplier Comment section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

Uncertainty Statement

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Legal Statement			
Supplier Acceptance *	true	Legal Declaration *	Standard

Legal Statement

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
STIH337ZCA/BD2	D2PP*H32AXAP	A	SA3A / 9988	27/6/2016
	Amount	UoM	Unit type	ST ECOPACK Grade
	498.9	mg	Each	ECOPACK® 2
Comment	ECOPACK® 2 is STMicroelectronics trade name for ROHS compliant device without Brominated and Chlorinated compound (900ppm) and without Antimony oxide flame retardant			

Manufacturing information			
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles	
3	260	3	
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment
SACN306	NAC	Copper Alloy	



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Package Designator	Size	Nbr of instances	Shape	
BGA	16x16	552	bulk solder	BSA: DM00271463 /BOM: 1F137281
Comment	Package : A06T FCBGA16x16x1.29 - 552 P0.65 B0.3 DM00187128			

QueryList : ROHS directive 2011/65/EU _ANNEX IV	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	TRUE
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	false
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	false
Exemption Id.	Description

QueryList : ELV directive : 2000/53/EC amended 2013/28/EU _May 2013	
Query	Response
1 - Product(s) meets EU ELV requirement without any exemptions	TRUE
2 - Product(s) meets EU ELV requirements by application of the selected exemption(s)	FALSE
Exemption Id.	Description

Query : California Prop65 list, dated 14 August 2015			
Query			Response
1 - The product does not contain identified substance from California Prop 65 List, no exposure to consumers is foreseen			FALSE
2 - The product is containing below substance(s) from California Prop 65 List, no exposure to consumers is foreseen			TRUE
Substance	amount in product (mg)	Application	ppm in product
Nickel	0.12	Die / Bump / Solder ball	241
Antimony trioxide	0.03	Solder ball	64

QueryList : REACH-20th June 2016				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				TRUE
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product
2 - Product(s) does not contain REACH Substances Of Very High Concern in any Homogeneous Material above the limits per the definition within REACH				TRUE
CategoryLevel_Name	CategoryLevel_Threshold	Amount in Homogeneous Material (mg)	Application - Homogeneous Material	ppm in Homogeneous Material

Material Composition Declaration						Mfr Item Name	D2PP*H32AXAP									
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)				
Die	Other inorganic materials	33.747	mg	supplier	die	Silicon (Si)	7440-21-3		29.353	mg	869796	58840				
				supplier	metallisation	Aluminium (Al)	7429-90-5		0.119	mg	3526	239				
				supplier	metallisation	Copper (Cu)	7440-50-8		0.528	mg	15646	1058				
				supplier	metallisation	Nickel (Ni)	7440-02-0		0.004	mg	119	8				
				supplier	metallisation	Tantalum (Ta)	7440-25-7		0.026	mg	770	52				
				supplier	metallisation	Titanium (Ti)	7440-32-6		0.004	mg	119	8				
				supplier	metallisation	Tungsten (W)	7440-33-7		0.002	mg	59	4				
				supplier	Passivation	Silicon Nitride (SiN)	12033-89-5		0.157	mg	4652	315				
				supplier	passivation	Silicon Oxide	7631-86-9		0.499	mg	14786	1000				
				supplier	die polymer coat	PIX1 Polyimide	108-65-6		0.413	mg	12238	828				
				supplier	UBM	Copper (Cu)	7440-50-8		0.005	mg	148	10				
				Bump	Metals	2.003	mg	Supplier	Metals	Titanium sputtering	7440-32-6		0.001	mg	331	1
								Supplier	Metals	Copper sputtering	7440-50-8		0.008	mg	3,928	16
Supplier	Metals	Copper plating	7440-50-8						1.049	mg	523,757	2,119				
Supplier	Metals	Nickel	7440-02-0						0.079	mg	39,238	159				
Supplier	Metals	Tin	7440-31-5						0.851	mg	424,956	1,719				
Supplier	Metals	Silver	7440-22-4						0.016	mg	7,789	32				
Substrate	Other organic materials	367.790	mg	Supplier	Core material	Epoxy in Core	Trade secret		78.757	mg	213,972	158,918				
				Supplier	Core material	Glass Cloth	65997-17-3		118.145	mg	320,958	238,376				
				Supplier	Through Hole fill	Epoxy in TH Filling resin	Trade secret		2.483	mg	6,751	5,014				
				Supplier	Through Hole fill	SiO2	7631-86-9		2.967	mg	8,068	5,992				
				Supplier	Through Hole fill	CaCO3	471-34-1		0.424	mg	1,153	856				
				Supplier	Through Hole fill	BaSO4	7727-43-7		0.182	mg	494	367				
				Supplier	ABF	Epoxy in ABF	Trade secret		18.670	mg	50,763	37,702				
				Supplier	ABF	SiO2	7631-86-9		3.295	mg	8,958	6,653				
				Supplier	Solder resist	Epoxy in Solder Mask	Trade secret		6.265	mg	17,034	12,651				
				Supplier	Solder resist	Barium Sulfate(BaSO4)	7727-43-7		1.959	mg	5,327	3,957				
				Supplier	Solder resist	Talc	14807-96-6		1.705	mg	4,637	3,444				
				Supplier	Solder resist	Silica	7631-86-9		0.835	mg	2,269	1,685				
				Supplier	Solder resist	other	Trade secret		1.330	mg	3,617	2,687				
				Supplier	Metals	Copper foil	7440-50-8		24.697	mg	67,149	49,872				
				Supplier	Metals	Copper plating	7440-50-8		106.337	mg	288,852	214,531				
				Underfill	Other organic materials	6.000	mg	Supplier	Glue	1, 6-bis (2,3 epoxypropoxy)naphthalene	27610-48-6		0.896	mg	149,254	1,808
								Supplier	Glue	Bisphenol F type liquid epoxy resin	9003-36-5		0.597	mg	99,502	1,206
Supplier	Glue	Bisphenol A type liquid epoxy resin	25068-38-6						0.149	mg	24,876	301				
Supplier	Glue	Aamine type harder	Trade secret						0.597	mg	99,502	1,206				
Supplier	Glue	Silicon Dioxide	60676-86-0						3.582	mg	597,015	7,234				
Supplier	Glue	Carbon black	1333-86-4						0.030	mg	4,975	60				
Supplier	Glue	Additives	Trade secret						0.149	mg	24,876	301				
Solder Ball	Solder	91.701	mg	Supplier	Solder	Tin	7440-31-5		88.331	mg	963,250	178,372				
				Supplier	Solder	Silver	7440-22-4		2.751	mg	30,000	5,555				
				Supplier	Solder	Copper	7440-50-8		0.550	mg	6,000	1,111				
				Supplier	Solder	Nickel	7440-02-0		0.037	mg	400	74				